Declaration of RoHS Compliant Products

Part Number: **Applicable to ASL, AFL, AHL, AXL-series.**

Product Name: **GaAs Amplifier**

Package Type: **TDFN8**

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Die	GaAs	1303-00-0	0.0836	100
Molding compound	Epoxy Resin A	trade secret	0.1445	3
	Epoxy Resin B	29690-82-2	0.1445	3
	Phenol Resin	trade secret	0.1445	3
	Metal Hydroxide	trade secret	0.1445	3
	Carbon black	1333-86-4	0.0241	0.5
	Silica(Amorphous)	60676-86-0	4.2138	87.5
Die attach	Sliver	7440-22-4	0.0633	78
	epoxy resin	9003-36-5	0.0097	12
	1,4-Bis(2,3-	2425-79-8	0.0041	5
	Dapsone	80-08-0	0.0041	5
Lead frame	Cu	7440-50-8	3.6205	97.22
	Fe	7439-89-6	0.0853	2.29
	P	7723-14-0	0.0011	0.03
	Zn	7440-66-6	0.0056	0.15
	Ag	7440-22-4	0.0115	0.31
Tin Plating	Tin	7440-31-5	0.3308	100
Gold Wire	Au	7440-57-5	0.0243	100
Total			**9.0598**	

This information sheet is to declare all substances intentionally added in our TDFN8 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr^{6+}), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which COMPLY with the *RoHS3 Directive 2015/863/EU*. For further information, contact our Sales Department at sales@asb.co.kr.

Authorized Signature, ASB Inc.

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.
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